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(54) **COMMON RAIL COOLING PLATE**

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(57) **ABSTRACT**

A cooling plate assembly to facilitate the cooling of electronic components, the cooling plate assembly including a cooling plate and a cooling chamber. The cooling chamber comprising a surface configured to receive a component to be cooled, a cooling chamber inlet, a common rail, a collection cavity, a plurality of cooling units fluidly coupled between the common rail and collection cavity, and a cooling chamber outlet fluidly coupled to the collection cavity.

